Amendments to the Claims

A detailed list of all claims under examination is set out below. Please add new claims 61-66 as shown below:

1-37. (Cancelled)

38. (previously presented): The article of claim 43 wherein the adhesive comprises a hot melt adhesive, pressure sensitive adhesive, curable adhesive, or filled adhesive.

39. (previously presented): The article of claim 38 wherein the adhesive comprises a filled electrically conductive adhesive, thermally conductive adhesive, or desiccating adhesive.

40. (previously presented): The article of claim 43 wherein there is a gap between the multi-layer structure and the surrounding adhesive.

41. (previously presented): The article of claim 43 wherein the article is an organic light emitting diode.

42. (previously presented): The article of claim 44 wherein the substrate comprises glass, the anode comprises indium tin oxide, the hole transporting layer comprises 4,4'-bis(naphthalen-2-yl)-N,N'-diphenyl benzidine, the light emitting layer comprises coumarin-doped tris(8-hydroxyquinolinato)aluminum, the electron transporting layer comprises bis(10-hydroxy-benzo(h)quinolinato) beryllium, bis(2-(2-hydroxy-phenyl)-benzolthiazolato) zinc, 3,4,5-triphenyl-1,2,4-triazole, or 2-(4-biphenylyl)-5-(4-*t*-butylphenyl)-1,3,4-oxadiazole, and the cathode comprises lithium fluoride and aluminum.

43. (previously presented): An article comprising an organic electronic device which comprises:

a. a substrate;

b. an adhesive;

c. a multi-layer structure comprising one or more organic layers between an anode and a cathode, the anode, cathode or an organic layer having at least one outer edge; and

d. a sealing layer;

wherein the adhesive seals an outer edge of an organic layer and has an opening through the adhesive that surrounds the multi-layer structure.

44. (previously presented): The article of claim 43 wherein the organic layers comprise a hole transporting layer, a light emitting layer, and an electron transporting layer.

45. (previously presented): The article of claim 40 further comprising a desiccant in the gap.

46. (previously presented): The article of claim 43 wherein the adhesive seals an outer edge of an anode or cathode.

47. (previously presented): The article of claim 43 wherein the adhesive seals all outer edges of an organic layer.

48. (previously presented): The article of claim 43 wherein the adhesive seals all outer edges of the multi-layer structure.

49. (previously presented): The article of claim 43 wherein the adhesive improves the device's structural stability.

50. (previously presented): The article of claim 43 wherein the adhesive and multi-layer structure have approximately equal thicknesses.

51. (previously presented): The article of claim 43 wherein the adhesive thickness is greater than the multi-layer structure thickness.

52. (previously presented): The article of claim 43 wherein the adhesive is on the substrate and the sealing layer is on the adhesive.

53. (previously presented): The article of claim 43 wherein the multi-layer structure is encapsulated by the adhesive and sandwiched between the substrate and sealing layer.

54. (previously presented): An article comprising an organic electronic device which comprises:

a. a roll of flexible substrate;

b. an adhesive;

c. a release liner; and

d. a multi-layer structure comprising one or more organic layers between an anode and a cathode, the anode, cathode or an organic layer having at least one outer edge;

wherein the adhesive and release liner have a combined thickness greater than the multi-layer structure thickness, and protect the multi-layer structure from damage in a roll to roll manufacturing process; and wherein the adhesive has an opening through it that surrounds the multi-layer structure.

55. (previously presented): The article of claim 54 wherein the adhesive seals an outer edge of an anode or cathode.

56. (previously presented): The article of claim 54 wherein the adhesive seals an outer edge of an organic layer.

57. (previously presented): The article of claim 54 wherein the adhesive seals all outer edges of an organic layer.

58. (previously presented): The article of claim 54 wherein the adhesive seals all outer edges of the multi-layer structure.

59. (previously presented): The article of claim 54 wherein the adhesive and multi-layer structure have approximately equal thicknesses.

60. (previously presented): The article of claim 54 wherein the adhesive and release liner have complementary openings.

61. (new): An organic electronic device precursor comprising:

a. a roll of flexible substrate comprising an electrode layer;

b. an adhesive;

c. a release liner; and

d. one or more organic layers on the electrode layer, the organic layer or layers having at least one outer edge;

wherein the adhesive and release liner have a combined thickness greater than the thickness of the organic layer or layers, and protect the organic layer or layers from damage in a roll to roll manufacturing process; and wherein the adhesive has an opening through it that surrounds the organic layer or layers.

62. (new): The precursor of claim 61 wherein the adhesive seals an outer edge of an electrode layer.

63. (new): The precursor of claim 61 wherein the adhesive seals all outer edges of an organic layer.

64. (new): The precursor of claim 61 wherein the adhesive seals all outer edges of all organic layers.

65. (new): The precursor of claim 61 wherein the adhesive and the organic layer or layers have approximately equal thicknesses.

66. (new): The precursor of claim 61 wherein the adhesive and release liner have complementary openings.